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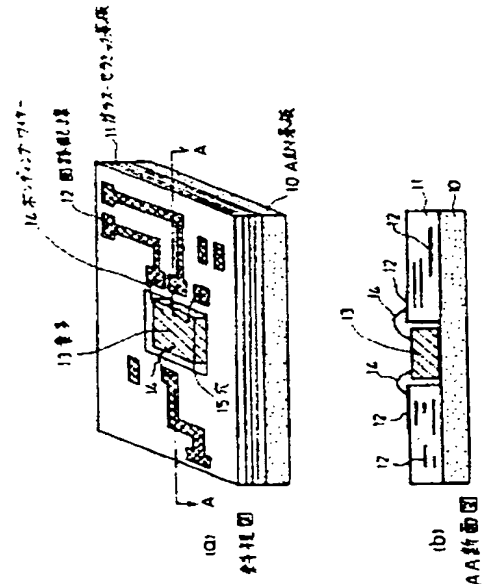
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APPLICANT : FUJITSU LTD;

INVENTOR : NIWA KOICHI;

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TITLE : CERAMIC CIRCUIT BOARD



ABSTRACT : PURPOSE: To reduce a ceramic circuit board in transmission loss and to improve it in heat dissipating property by a method wherein a glass-ceramic wiring board is joined to a base board of high thermal conductivity, and an element is mounted on the base board.

CONSTITUTION: A wiring board 11 is formed of glass-ceramic whose dielectric constant is 5 or so as an insulating material, a base board 10 is formed of good thermal conductor, for instance, aluminum nitride whose thermal conductivity is larger than that of alumina, the boards 10 and 11 are joined together, and an element 13 housed in a hole 15 provided to the board 11 is directly bonded to the base board 10. By this setup, a bonding wire 14 can be made short to reduce the delay of transmission signal, the transmission loss is reduced in a high frequency region because the wiring board 11 has a low dielectric constant, and moreover the element 13 is improved in heat dissipation.

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